

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	HD01	HD02	HD04	HD06	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RMM} V _{RWM} V _{DC}	100	200	400	600	V
RMS Reverse Voltage	V _{RMS}	70	140	280	420	V
Average Forward Rectified Current (Note 4) @T _A = +40°C	lo		0	.8		Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}		3	30		Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 4)	$R_{\theta JA}$	75	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

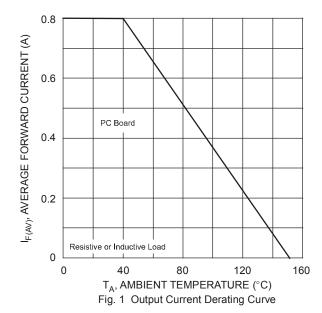
Characteristic	Symbol	Value	Unit
Instantaneous Voltage Drop @ 0.4A (Per Element)	V _F	1.0	V
Peak Reverse Current at Rated @T _A = +25°C	4	5.0	μA
DC Blocking Voltage (Per Element) @T _A = +125°C	IR	500	μΛ
Typical Total Capacitance (Per Element) (Note 5)	C _T	10	pF

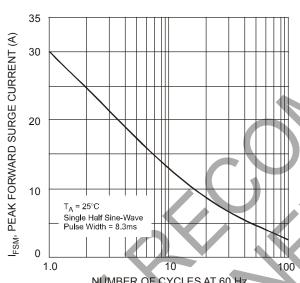
Notes:

- 4. Mounted on PC Board.
- 5. Measured at 1.0MHz and applied reverse voltage of 4.0V.

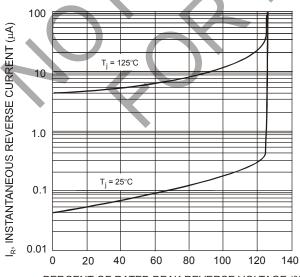








NUMBER OF CYCLES AT 60 Hz Fig. 3 Maximum Peak Forward Surge Current (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%) Fig. 5 Typical Reverse Characteristics (per element)

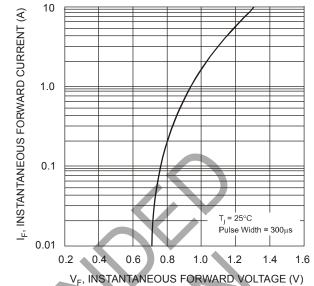


Fig. 2 Typical Forward Characteristics (per element)

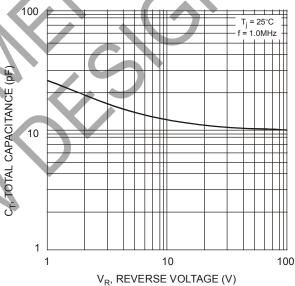


Fig. 4 Typical Total Capacitance (per element)

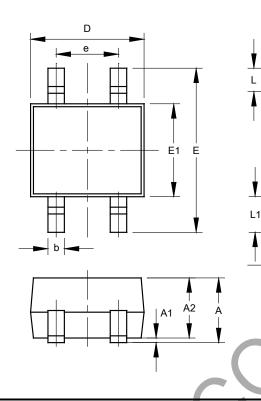


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

MiniDIP

A2a

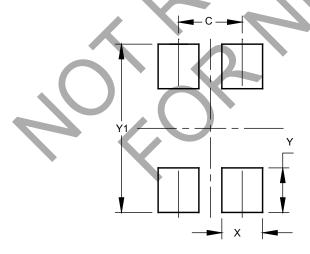


MiniDIP			
Dim	Min	Max	
Α		3.00	
A1		0.20	
A2	2.30	2.70	
A2a	1.20	1.60	
b	0.50	0.80	
С	0.15	0.35	
D	4.50	4.90	
Е		7.00	
E1	3.60	4.00	
е	2.30	2.70	
L	0.70	1.10	
L1	1.10	2.12	
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

MiniDIP



Dimensions	Value (in		
Dillielisions	mm)		
С	2.50		
Х	1.65		
Υ	1.80		
Y1	6.80		



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